# 2-2129710-8 - ACTIVE

TE Internal #: 2-2129710-8 LGA Sockets, LGA 3647, 1823 Position, .034 in / .039 in [.86 mm / . 99 mm] Centerline, Surface Mount Solder Ball Mount View on TE.com >



Connectors > Socket Connectors > IC Sockets > LGA Sockets > LGA 3647 Sockets



IC Socket Type: LGA 3647 Connector System: Board-to-Board Number of Positions: 1823 Contact Mating Area Plating Material Thickness: [30 µin] Centerline (Pitch): .86 mm, .99 mm [.034 in, .039 in]

#### All LGA 3647 Sockets (8)

#### Features

#### Product Type Features

Connector System

Board-to-Board

Connector & Contact Terminates To

Printed Circuit Board

## **Configuration Features**

Number of Positions	1823
Grid Spacing	.9906 x .8585 mm[.039 x .0338 in]
Body Features	
Frame Style	C Shape
Contact Features	
Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
	30 µin
Contact Current Rating (Max)	.5 A
Mechanical Attachment	
PCB Mounting Style	Surface Mount Solder Ball
Connector Mounting Type	Board Mount
Housing Features	

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Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.86 mm, .99 mm[.034 in][.039 in]
Usage Conditions	
Operating Temperature Range	-25 – 100 °C[-13 – 212 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Tray Color	Blue
Packaging Method	Tray
Other	
Socket Connector Comment	Lead-Free Solderball

# Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant	
EU ELV Directive 2000/53/EC	Compliant	
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold	
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC	
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free	
Solder Process Capability	Reflow solder capable to 260°C	
Product Compliance Disclaimer This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products		

will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous

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materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts



TE Part # 2821719-1 IFP/LEC CBL ASSY 2 PORT TYPE A STR



TE Part # 2821719-2 IFP/LEC CBL ASSY 2 PORT TYPE A STR



TE Part # 2821719-3 IFP/LEC CBL ASSY 2 PORT TYPE A STR



TE Part # 2821719-4 IFP/LEC CBL ASSY 2 PORT TYPE A STR



# Customers Also Bought



#### Documents

Product Drawings RIGHT SIDE LGA3647-1 SOCKET-P1 FOR ODM

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English **CAD** Files 3D PDF 3D **Customer View Model** ENG\_CVM\_CVM\_2-2129710-8\_C.2d\_dxf.zip English **Customer View Model** ENG\_CVM\_CVM\_2-2129710-8\_C.3d\_igs.zip English Customer View Model ENG\_CVM\_CVM\_2-2129710-8\_C.3d\_stp.zip English By downloading the CAD file I accept and agree to the Terms and Conditions of use Datasheets & Catalog Pages LGA 3647 Socket Product Flyer English **Product Specifications** 

**Application Specification** 

English